

## **Product Summary**

V <sub>(BR)DSS</sub>	V <sub>(BR)DSS</sub> R <sub>DS(on)TYP</sub>	
-100V	10mΩ@-10V	-120A



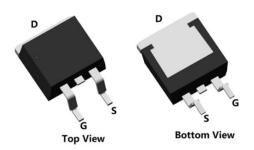
#### **Feature**

- Fast Switching
- Low Gate Charge and Rdson
- Advanced Split Gate Trench Technology
- 100% Single Pulse avalanche energy Test

#### **Applications**

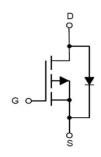
- PWM Application
- Hard switched and high frequency circuits
- Power Management

## **Package**

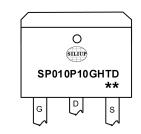


TO-263(1:G 2:D 3:S)

## Circuit diagram



# Marking



SP010P10GHTD :Device Code \*\* :Week Code

#### **Order Information**

Device	Package	Unit/Tape
SP010P10GHTD	TO-263	800

100V P-Channel Power MOSFET

# Absolute maximum ratings (Ta=25°C,unless otherwise noted)

Parameter	Symbol	Rating	Units
Drain-Source Voltage	V <sub>DS</sub>	-100	V
Gate-Source Voltage	V <sub>GS</sub>	±20	V
Continuous Drain Current(Tc=25°C)	ID	-120	А
Continuous Drain Current(Tc=100℃)	I <sub>D</sub>	-80	А
Pulsed Drain Current	I <sub>DM</sub>	-480	А
Single Pulse Avalanche Energy <sup>1</sup>	Eas	820	mJ
Power Dissipation(Tc=25°C)	P <sub>D</sub>	232	W
Thermal Resistance Junction-to-Case	R <sub>θJC</sub>	0.54	°C/W
Storage Temperature Range	T <sub>STG</sub>	-55 to 150	°C
Operating Junction Temperature Range	T <sub>J</sub>	-55 to 150	$^{\circ}$

# Electrical characteristics (Ta=25°C, unless otherwise noted)

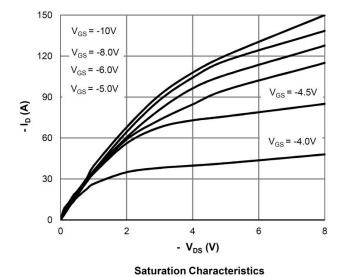
Parameter	Symbol	Conditions	Min.	Тур.	Max.	Unit
Static Characteristics						
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	VGS=0V , ID= -250uA	-100	-	-	V
Drain-Source Leakage Current	I <sub>DSS</sub>	VDS=-80V , VGS=0V , TJ=25℃	-	-	-1	uA
Gate-Source Leakage Current	I <sub>GSS</sub>	VGS=±20V, VDS=0V	-	-	±100	nA
Gate Threshold Voltage	V <sub>GS(th)</sub>	VGS=VDS , ID = -250uA	-2	-3	-4	V
Static Drain-Source On-Resistance	R <sub>DS(ON)</sub>	VGS=-10V , ID= -20A	-	10	13	mΩ
Dynamic characteristics						
Input Capacitance	Ciss	VDS=-50V , VGS=0V , f=1MHz		13600	-	
Output Capacitance	Coss			1200	-	pF
Reverse Transfer Capacitance	Crss			26	-	
Total Gate Charge	Qg	VDS=-50V , VGS=10V , ID=-20A		168	-	
Gate-Source Charge	Q <sub>gs</sub>			46	-	nC
Gate-Drain Charge	Q <sub>gd</sub>			23	-	
Switching Characteristics						
Turn-On Delay Time	T <sub>d(on)</sub>			16	-	
Rise Time	Tr	VDD- 50V VCC-40V BC-4 50 ID- 20A	-	58	-	
Turn-Off Delay Time	T <sub>d(off)</sub>	- VDD=-50V , VGS=10V , RG=1.6Ω,ID=-20A		145	-	ns
Fall Time	T <sub>f</sub>			56	-	
Diode Characteristics				•		
Diode Forward Voltage	V <sub>SD</sub>	VGS=0V , I <sub>S</sub> =-1A , TJ=25°C	-	-	-1.2	V
Maximum Body-Diode Continuous Current	Is		-	-	-120	Α
Reverse Recovery Time	Trr	I <sub>S</sub> =-20A, di/dt=100A/us, TJ=25℃		96	-	ns
Reverse Recovery Charge	Qrr			205	_	nC

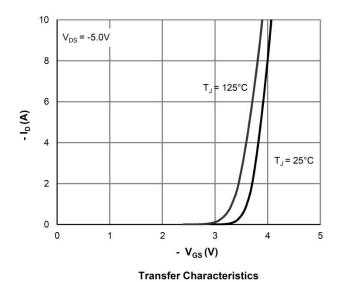
## Note:

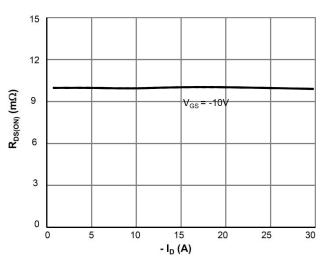
**1.** The test condition is VDD=-50V,VGS=-10V,L=0.5mH,RG=25 $\Omega$ 

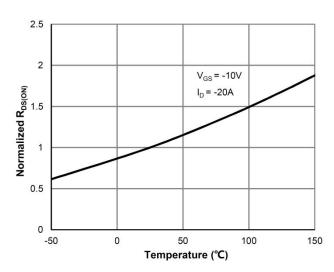


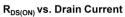
## **Typical Characteristics**



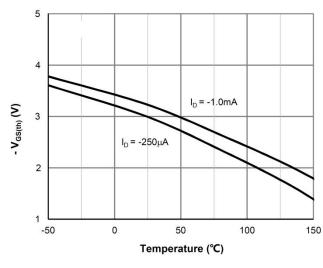


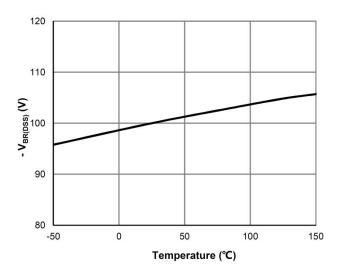






R<sub>DS(ON)</sub> vs. Junction Temperature

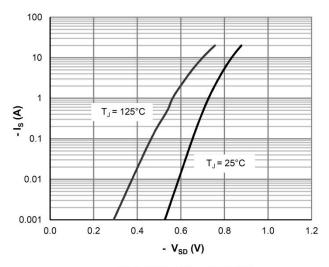


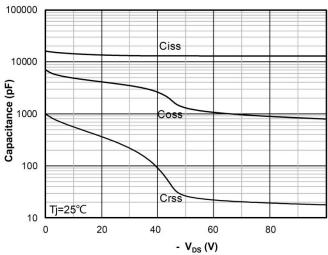


 $V_{\text{GS(th)}}$  vs. Junction Temperature

 $V_{BR(DSS)}$  vs. Junction Temperature

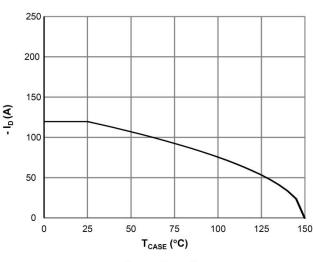


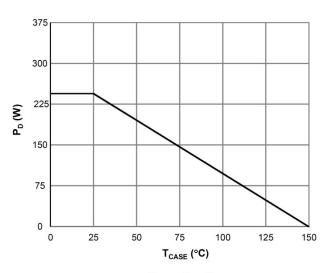




**Body-Diode Characteristics** 

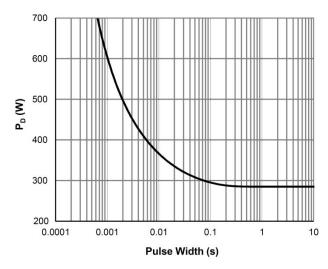
**Capacitance Characteristics** 

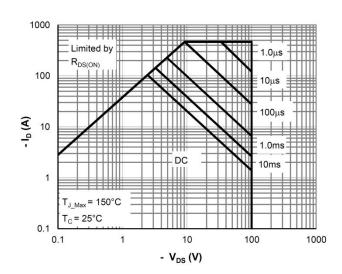




Current De-rating

Power De-rating

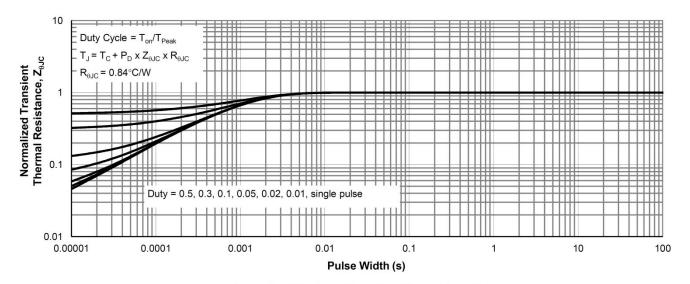




Single Pulse Power Rating, Junction-to-Case

Maximum Safe Operating Area

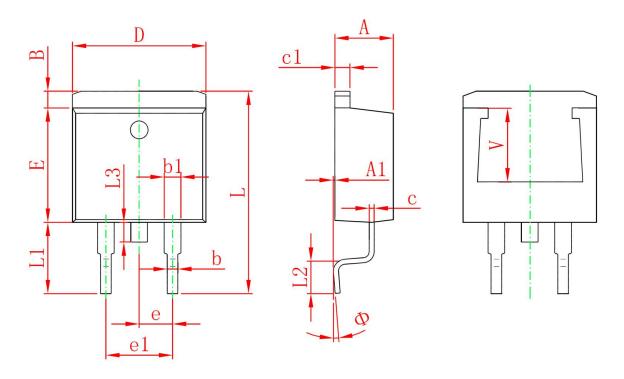




**Normalized Maximum Transient Thermal Impedance** 

100V P-Channel Power MOSFET

# TO-263 Package Information



	Dimensions In Millimeters		Dimensions In Inches		
Symbol	Min.	Max.	Min.	Max.	
А	4.470	4.670	0.176	0.184	
A1	0.000	0.150	0.000	0.006	
В	1.120	1.420	0.044	0.056	
b	0.710	0.910	0.028	0.036	
b1	1.170	1.370	0.046	0.054	
С	0.310	0.530	0.012	0.021	
c1	1.170	1.370	0.046	0.054	
D	10.010	10.310	0.394	0.406	
E	8.500	8.900	0.335	0.350	
е	2.540	2.540 TYP.		TYP.	
e1	4.980	5.180	0.196	0.204	
L	14.940	15.500	0.588	0.610	
L1	4.950	5.450	0.195	0.215	
L2	2.340	2.740	0.092	0.108	
L3	1.300	1.700	0.051	0.067	
Ф	0°	8°	0°	8°	
V	5.600 REF.		0.220 REF.		